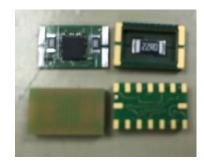


Data Sheet - SIP

System In Package



DESCRIPTION

Lingsen' SIP is a substrate based, with surface mount process., with encapsulated lid package. It is available in pin count is 16 or can be customized to individual customer needs.

APPLICATIONS

■ Module

FEATURES

- Pin count range is 16.
- Lead pitch of 2 mm.

SPECIFICATIONS

Substrate: FR4
Solder SAC305

Packing: 150DegC PPE tray

PACKAGE AVAILABILITY

Package Size Lead Pitch Lead Count (mm) (mm) 8 x 13 2 16

RELIABILITY

MSL 60°C/60%RH 168h +

IR*3times

Thermal shock -40degC<->85degC(each

30minutes), 200cycle

High temperature storage 95degC,1000hrs
Low temperature storage -40degC,1000hrs

Damp heat storage 85degC,85%RH,1000hrs





Data Sheet - SIP

System In Package

CROSS-SECTION

